

## C&D P8000 Lift-Off System



### Description

The P8000 Lift-off System is a fully automated system designed for metal lift-off application.

The cassette to cassette design offers a reduced overall system footprint.

C&D uses a low pressure spray to soak the wafer for a programmed duration - this is followed by a high pressure fine needle spray. The programmed arm sweeps across the wafer to evenly lift off unwanted metal.

With four independent dispense lines, the systems offers flexibility for the user to create a recipe that optimizes their specific requirements.

High accuracy spin and arm control ensures that all areas across the wafer see the same exposure to the lift off solvents.

The system can be configured with a diverting valve to separate solvents from DI water in the waste streams.

### Benefits

**Programmable arm movement covers the full wafer diameter during each single cycle to cleanly lift off metal.**

- » Even spray across wafer
- » Adjustable duration speed across wafer
- » Z-axis control for low and high pressure spray nozzles with respect to wafer

**The system is designed to improve process capability and reduce contamination.**

- » Backwash prevents metal getting on underside of wafer
- » Air ring keeps the back of the wafer and the chuck completely dry during processing.
- » Process chamber is designed to reduce misting and splash back.
- » Exceptional fume control

### System Features

- » Process 50 mm – 200 mm substrates
- » Programmable arm with combination of spray, puddle, and high pressure spray
- » Brushless motor with digital spindle controller
- » Metal lift-off chemistries: Acetone, IPA, NMP, and more
- » Throughput is 8-20 wafers per hour (process dependent)
- » Various solutions to precious metal capture
- » PC Windows-based operating system with smartPro GUI
- » Unlimited recipe programming
- » CE mark certifies the system's compliance with EU requirements

## Options

- » Diverting drain
- » Heated solvent capability
- » SECS/GEM capability
- » Custom chemical cabinets
- » System enclosure
- » Fire suppression
- » Dual wafer size processing without hardware change
- » Contact C&D for more options

